

### PROTECTION PRODUCTS

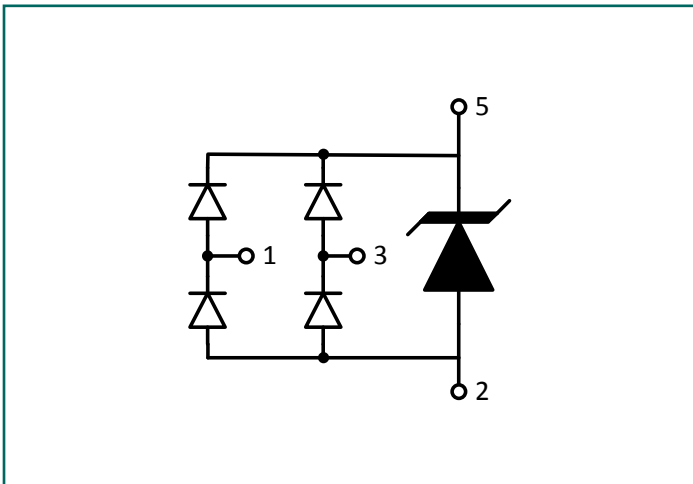
#### Description

TClamp<sup>®</sup>xx82S are specifically designed to provide secondary surge and ESD protection for G.Fast and other DSL circuit line drivers. These devices integrate low capacitance, surge-rated steering diodes with a high power transient voltage suppressor (TVS). The TVS utilizes snap-back or "crow-bar" technology to minimize device clamping voltage and features high surge current capability of 30A ( $t_p=8/20\mu s$ ).

TClampxx82S capacitance is limited to 2.5pF maximum with a low typical capacitance variation over the operating voltage range. This ensures correct signal transmission on DSL lines. The biased bridge structure allows the device to be used in G.Fast, ADSL, and VDSL applications with with operating voltages of 8, 12, 20, and 24Vp-p.

TClampxx82S is in a 6-pin SOT-23 package. The leads are finished with lead-free matte tin. The flow-through package design simplifies PCB layout.

#### Circuit Diagram



#### Features

- Transient Protection to
  - ♦ IEC 61000-4-2 (ESD) 30kV (Air), 30kV (Contact)
  - ♦ IEC 61000-4-4 (EFT) 2kV (5/50ns)
  - ♦ IEC 61000-4-5 (Lightning) 30A (8/20 $\mu s$ )
- Bias diodes prevent charging of TVS capacitance
- Working Voltage Options: 8V, 12V, 20V, 24V
- Low Capacitance: 2.5pF Maximum
- Low Capacitance Variation (1V to  $V_{RWM}$ )
- Solid-State Silicon-Avalanche Technology

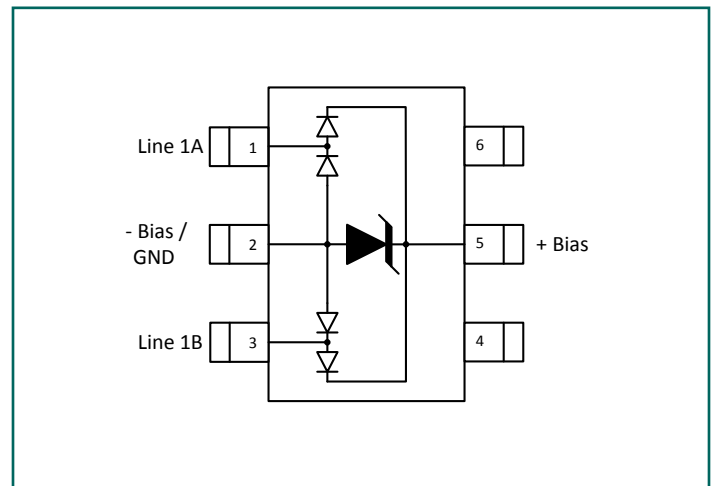
#### Mechanical Characteristics

- JEDEC SOT-23 6L package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Lead Finish: Matte Tin
- Molding Compound Flammability Rating: UL 94V-0
- Marking : Marking Code + Date Code
- Packaging : Tape and Reel

#### Applications

- ADSLx / VDSLx Secondary Protection
- G.Fast Line Driver Secondary Protection
- VDSL2 Class-H Line Driver Secondary Protection
- Modems
- Access Equipment
- Central Office Equipment
- Customer Premise Equipment

#### Pin Configuration



## Absolute Maximum Ratings

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P <sub>PK</sub>	300	W
Peak Pulse Current (tp = 8/20μs)	I <sub>PP</sub>	30	A
ESD per IEC 61000-4-2 (Contact) <sup>(1), (3)</sup>	V <sub>ESD</sub>	±30	kV
Operating Temperature	T <sub>J</sub>	-40 to +85	°C
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (T=25°C unless otherwise specified)

TClamp0882S							
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units	
Reverse Stand-Off Voltage	V <sub>RWM</sub>	-40°C to 85°C Pin 1 or 3 to Pin 2, Pin 1 to Pin 3			8	V	
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>BR</sub> = 10mA, T = -40°C to 85°C Pin 1 to Pin 3	13.5	15.5	18	V	
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 8V	T = 25°C		0.01	0.100	μA
			T = 85°C		0.02	0.100	μA
Holding Current <sup>(3)</sup>	I <sub>H</sub>		50	125		mA	
Clamping Voltage <sup>(2), (3)</sup>	V <sub>C</sub>	I <sub>PP</sub> = 30A, tp = 1.2/50μs, 8/20μs Combination Waveform Pin 1 to Pin 3		9.5		V	
Breakover Voltage <sup>(3)</sup>	V <sub>BO</sub>	I <sub>BO</sub> = 50mA Pin 1 to Pin 3			23	V	
Junction Capacitance	C <sub>J</sub>	V <sub>R</sub> = 0V, f = 1MHz Pin 1 to 3		1.2	2.5	pF	
Variation in Junction Capacitance <sup>(3)</sup>	ΔC <sub>J</sub>	V <sub>R</sub> = 1V - 8V, f = 1MHz Pin 1 to Pin 3		0.15		pF	

### Notes:

(1): ESD Gun return path to Ground Reference Plane (GRP)

(2): Measured using a 1.2/50us voltage, 8/20us current combination waveform, RS = 2 Ohms. Clamping is defined as the peak voltage across the device after the device snaps back to a conducting state.

(3): Guaranteed by design. Not production tested

## Absolute Maximum Ratings

### Electrical Characteristics (T=25°C unless otherwise specified)

TClamp1282S							
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units	
Reverse Stand-Off Voltage	$V_{RWM}$	-40°C to 85°C Pin 1 or 3 to Pin 2, Pin 1 to Pin 3			12	V	
Reverse Breakdown Voltage	$V_{BR}$	$I_{BR} = 10\text{mA}$ , T = -40°C to 85°C Pin 1 to Pin 3	15.5	18.5	22	V	
Reverse Leakage Current	$I_R$	$V_{RWM} = 12\text{V}$	T = 25°C		0.01	0.100	μA
			T = 85°C		0.02	0.100	μA
Holding Current <sup>(3)</sup>	$I_H$		50	125		mA	
Clamping Voltage <sup>(2), (3)</sup>	$V_C$	$I_{pp} = 30\text{A}$ , $t_p = 1.2/50\mu\text{s}$ , $8/20\mu\text{s}$ Combination Waveform Pin 1 to Pin 3		9.5		V	
Junction Capacitance	$C_J$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Pin 1 to 3	T = 25°C		1.2	2.5	pF
Variation in Junction Capacitance <sup>(3)</sup>	$\Delta C_J$	$V_R = 1\text{V} - 12\text{V}$ , $f = 1\text{MHz}$ Pin 1 to Pin 3		0.15		pF	

Notes:

(1): ESD Gun return path to Ground Reference Plane (GRP)

(2): Measured using a 1.2/50us voltage, 8/20us current combination waveform, RS = 2 Ohms. Clamping is defined as the peak voltage across the device after the device snaps back to a conducting state.

(3): Guaranteed by design. Not production tested

## Absolute Maximum Ratings

### Electrical Characteristics (T=25°C unless otherwise specified)

TClamp2082S							
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units	
Reverse Stand-Off Voltage	$V_{RWM}$	-40°C to 85°C Pin 1 or 3 to Pin 2, Pin 1 to Pin 3			20	V	
Reverse Breakdown Voltage	$V_{BR}$	$I_{BR} = 10\text{mA}$ , T = -40°C to 85°C Pin 1 to Pin 3	23	26.5	30	V	
Reverse Leakage Current	$I_R$	$V_{RWM} = 20\text{V}$	T = 25°C		0.01	0.100	μA
			T = 85°C		0.02	0.100	μA
Holding Current <sup>(3)</sup>	$I_H$		50	125		mA	
Clamping Voltage <sup>(2), (3)</sup>	$V_C$	$I_{PP} = 30\text{A}$ , $t_p = 1.2/50\mu\text{s}$ , $8/20\mu\text{s}$ Combination Waveform Pin 1 to Pin 3		9.5		V	
Breakover Voltage <sup>(3)</sup>	$V_{BO}$	$I_{BO} = 50\text{mA}$ Pin 1 to Pin 3			23	V	
Junction Capacitance	$C_J$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Pin 1 to 3		1.2	2.5	pF	
Variation in Junction Capacitance <sup>(3)</sup>	$\Delta C_J$	$V_R = 1\text{V} - 20\text{V}$ , $f = 1\text{MHz}$ Pin 1 to Pin 3		0.4		pF	

Notes:

(1): ESD Gun return path to Ground Reference Plane (GRP)

(2): Measured using a 1.2/50us voltage, 8/20us current combination waveform, RS = 2 Ohms. Clamping is defined as the peak voltage across the device after the device snaps back to a conducting state.

(3): Guaranteed by design. Not production tested

## Absolute Maximum Ratings

### Electrical Characteristics (T=25°C unless otherwise specified)

TClamp2482S							
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units	
Reverse Stand-Off Voltage	$V_{RWM}$	-40°C to 85°C Pin 1 or 3 to Pin 2, Pin 1 to Pin 3			24	V	
Reverse Breakdown Voltage	$V_{BR}$	$I_{BR} = 10\text{mA}$ , T = -40°C to 85°C Pin 1 to Pin 3	27	31	35	V	
Reverse Leakage Current	$I_R$	$V_{RWM} = 24\text{V}$	T = 25°C		0.01	0.100	μA
			T = 85°C		0.02	0.100	μA
Holding Current <sup>(3)</sup>	$I_H$		50	125		mA	
Clamping Voltage <sup>(2), (3)</sup>	$V_C$	$I_{PP} = 30\text{A}$ , $t_p = 1.2/50\mu\text{s}$ , $8/20\mu\text{s}$ Combination Waveform Pin 1 to Pin 3		9.5		V	
Breakover Voltage <sup>(3)</sup>	$V_{BO}$	$I_{BO} = 50\text{mA}$ Pin 1 to Pin 3			35	V	
Junction Capacitance	$C_J$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Pin 1 to 3		1.2	2.5	pF	
Variation in Junction Capacitance <sup>(3)</sup>	$\Delta C_J$	$V_R = 1\text{V} - 24\text{V}$ , $f = 1\text{MHz}$ Pin 1 to Pin 3		0.4		pF	

Notes:

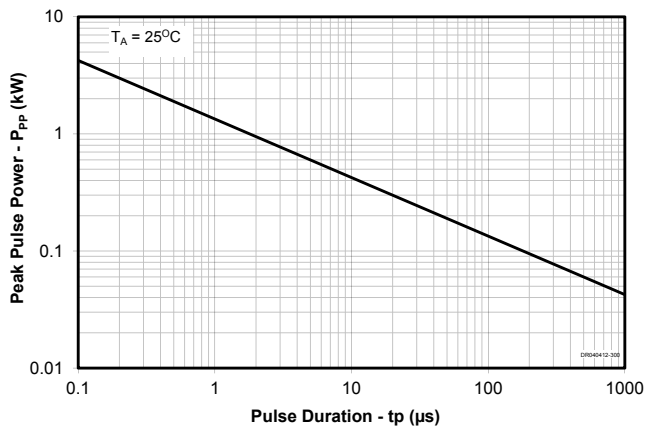
(1): ESD Gun return path to Ground Reference Plane (GRP)

(2): Measured using a 1.2/50us voltage, 8/20us current combination waveform, RS = 2 Ohms. Clamping is defined as the peak voltage across the device after the device snaps back to a conducting state.

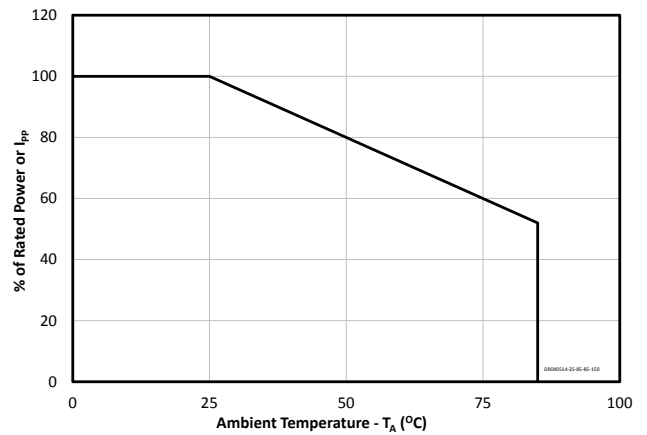
(3): Guaranteed by design. Not production tested

# Typical Characteristics

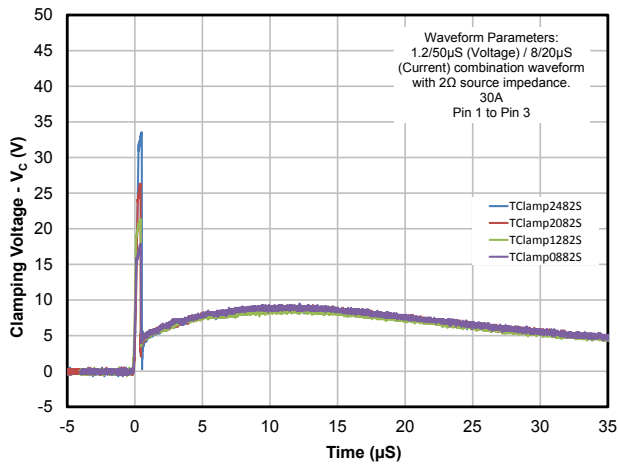
### Non-Repetitive Peak Pulse Power vs. Pulse Time



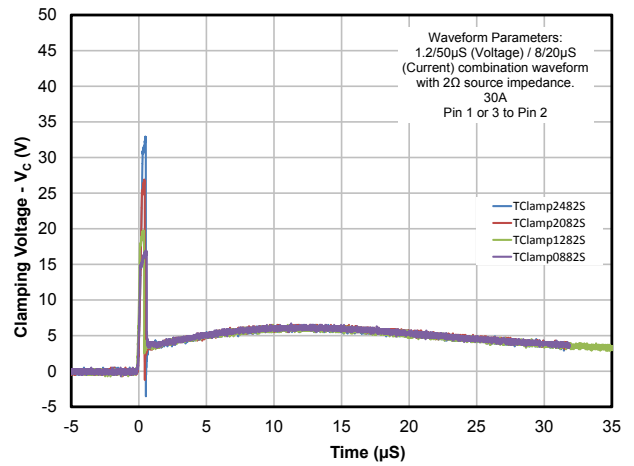
### Power Derating Curve



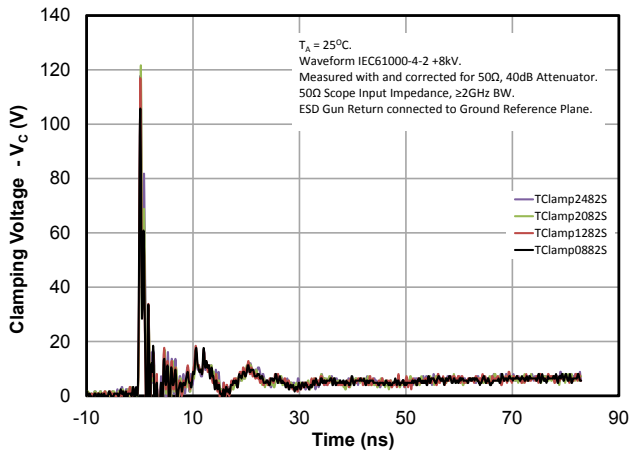
### Clamping Characteristic (I/O to I/O, Pin 1-3)



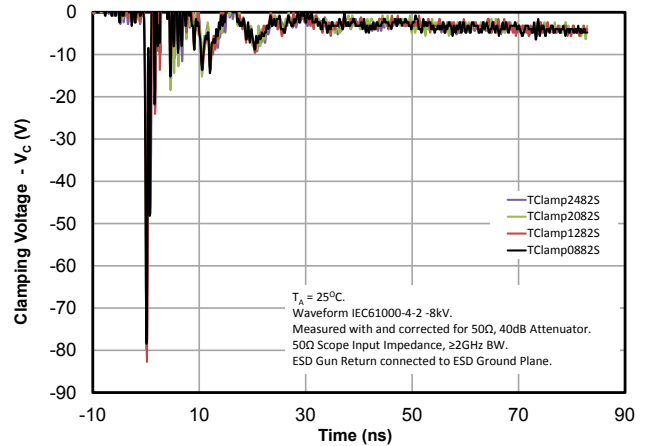
### Clamping Characteristic (I/O to GND, Pin 1 or 3 to 2)



### ESD Clamping (+8kV Contact per IEC 61000-4-2)

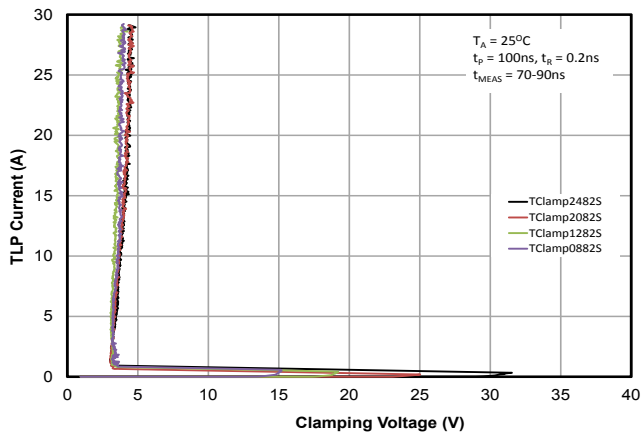


### ESD Clamping (-8kV Contact per IEC 61000-4-2)

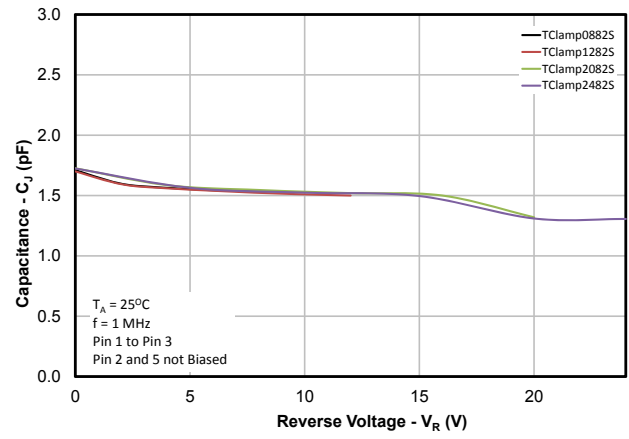


# Typical Characteristics

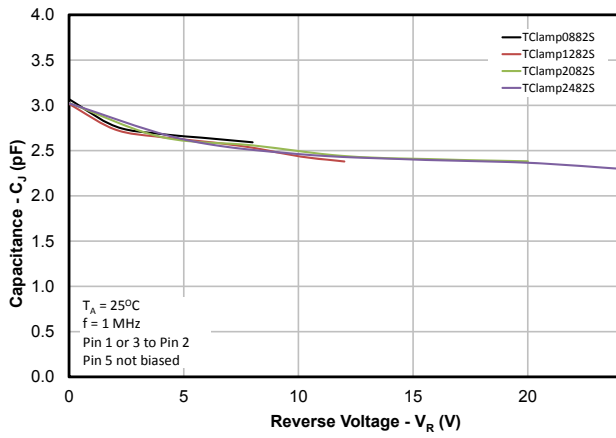
## TLP Characteristic



## Capacitance vs. Reverse Voltage (Pin 1 to 3)



## Capacitance vs. Reverse Voltage (Pin 1 or 3 to Pin 2)



# Applications Information

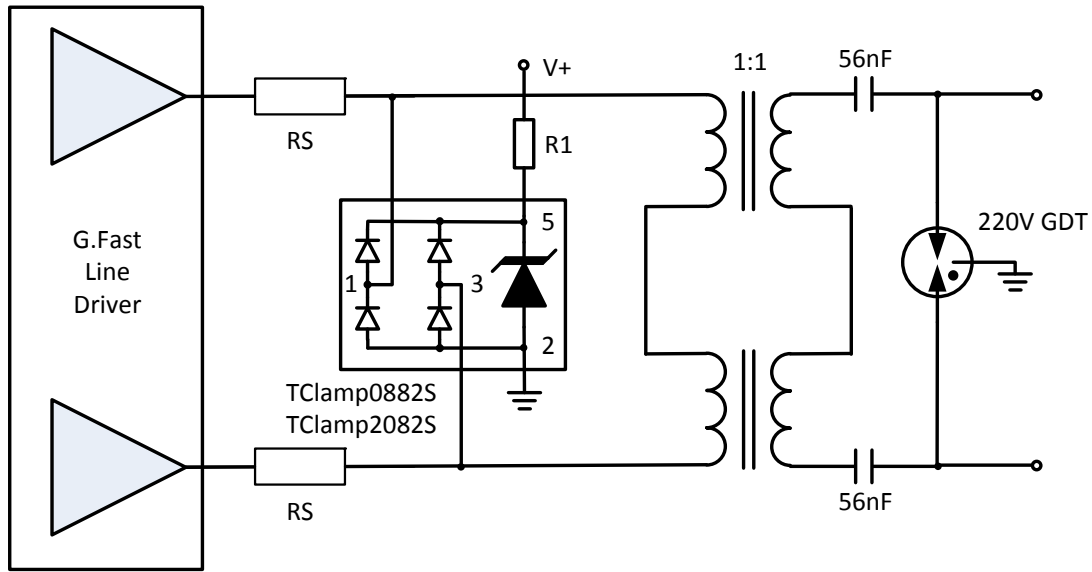


Figure 1 - Typical G.Fast Protection Circuit

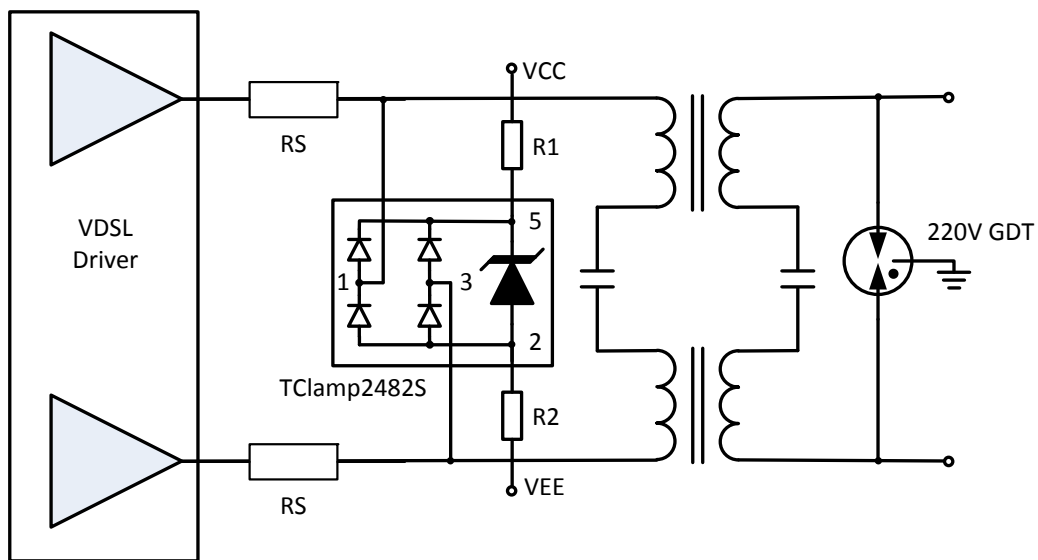


Figure 2 - Typical VDSL Class-H Protection Circuit



# Applications Information

## Device Connection and PCB Routing

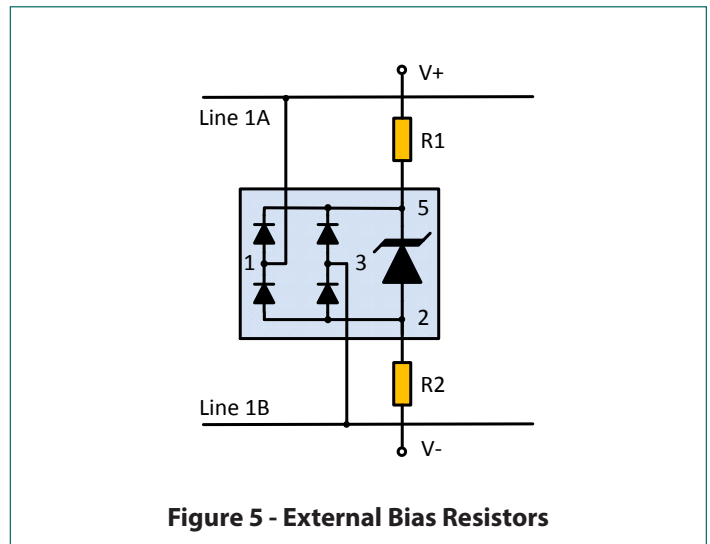
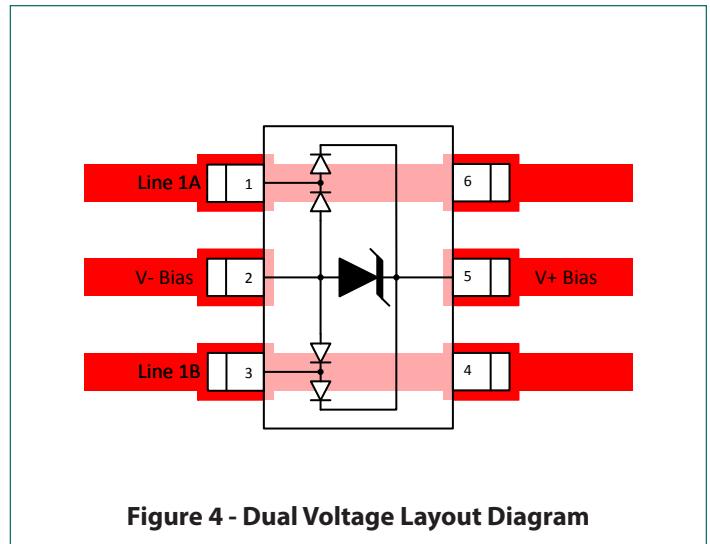
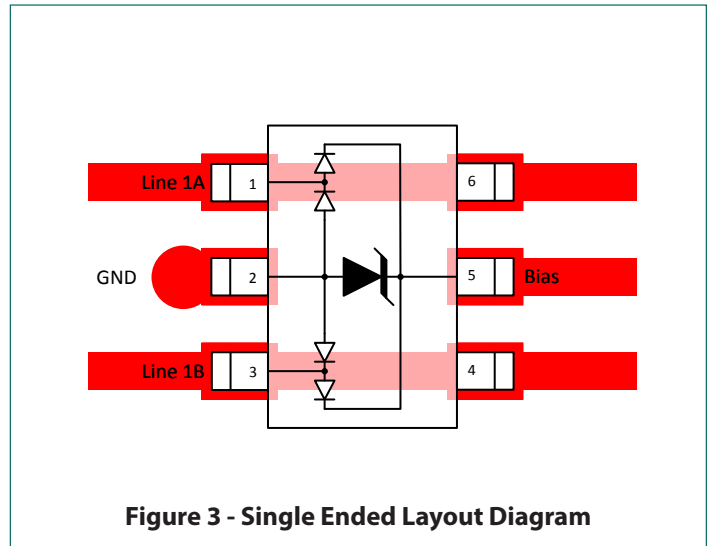
The flow-through design of TClampxx82S simplifies board layout and PCB trace routing. The device can be configured for single ended applications such as G.Fast CPE (Figure 3) or dual voltage applications such as VDSL (Figure 4). Line 1A is connected at pin1 and its trace can continue under the part and connect to pin 6, which is not connected internally to the part. A similar connection can be made for Line 1B. This layout makes it easy to keep the differential signal traces symmetrical.

### Bias

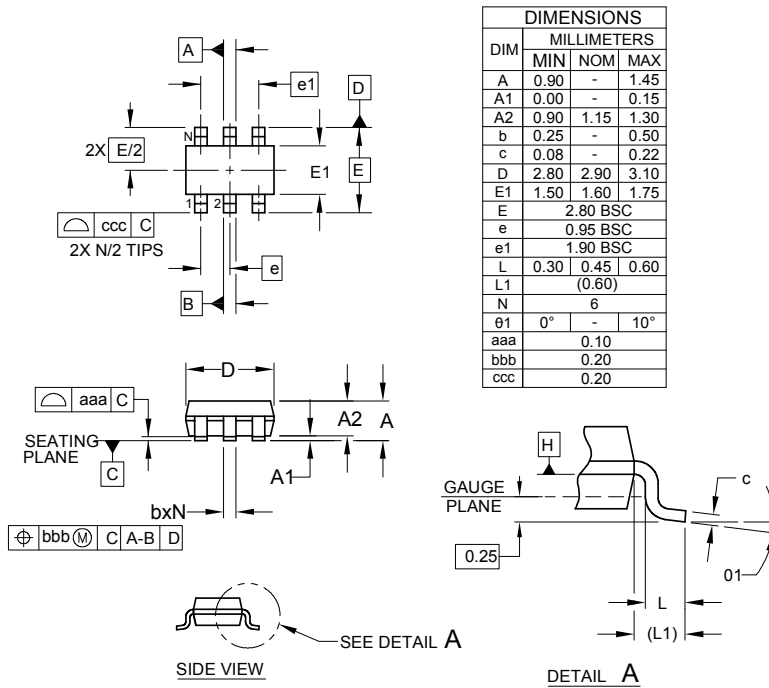
The device uses an internal bridge structure to effectively hide the capacitance of the TVS diode. However, in high voltage applications such as DSL, the initial signal will charge the capacitance of the TVS causing signal distortion and transmission errors. This distortion is only present until the TVS capacitance becomes charged and stabilizes. The solution is to pre-bias the TVS capacitance by connecting it to the external supply voltage (Figure 5). In the case of TClampxx82s, positive bias voltage should be connected at pin 5. For single ended applications, pin 2 is connected to ground (as shown in Figure 3). For dual voltage applications, pin 2 should be connected to negative polarity bias voltage. The bias resistors (R1, R2) should be large enough value as to minimize leakage current and minimize voltage drop over temperature (typically 100K Ohms to 1 Meg Ohm).

### Surge and Power Induction Testing

DSL interfaces are wired telecom networks which are exposed to EOS from lightning surges and AC power line induction. DSL circuits are normally tested to the immunity requirements of ITU-T K.20, K.21, and K.44. TClampxx82S is designed to provide secondary protection to xDSL and G.Fast line drivers. They have been tested and passed the above requirements when used in conjunction with 220V gas discharge tubes (GDT). For more details, reference Semtech application note SI16-03 "Protecting G.Fast Circuits from Power Induction and Lightning Surges".



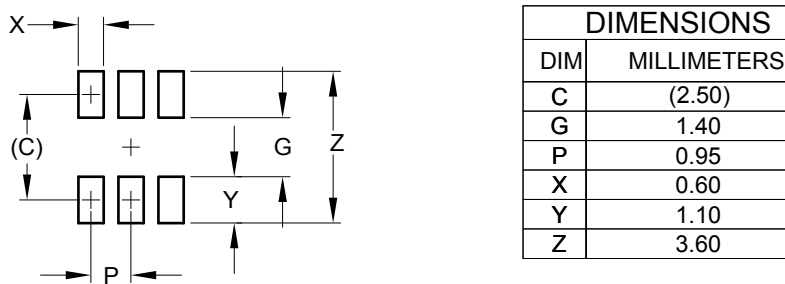
## Outline Drawing - SOT-23 6L



**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**.
3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

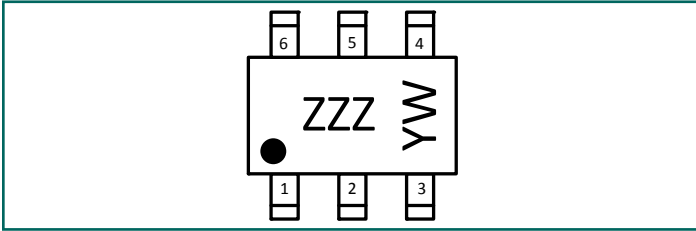
## Land Pattern - SOT-23 6L



**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

## Marking Example



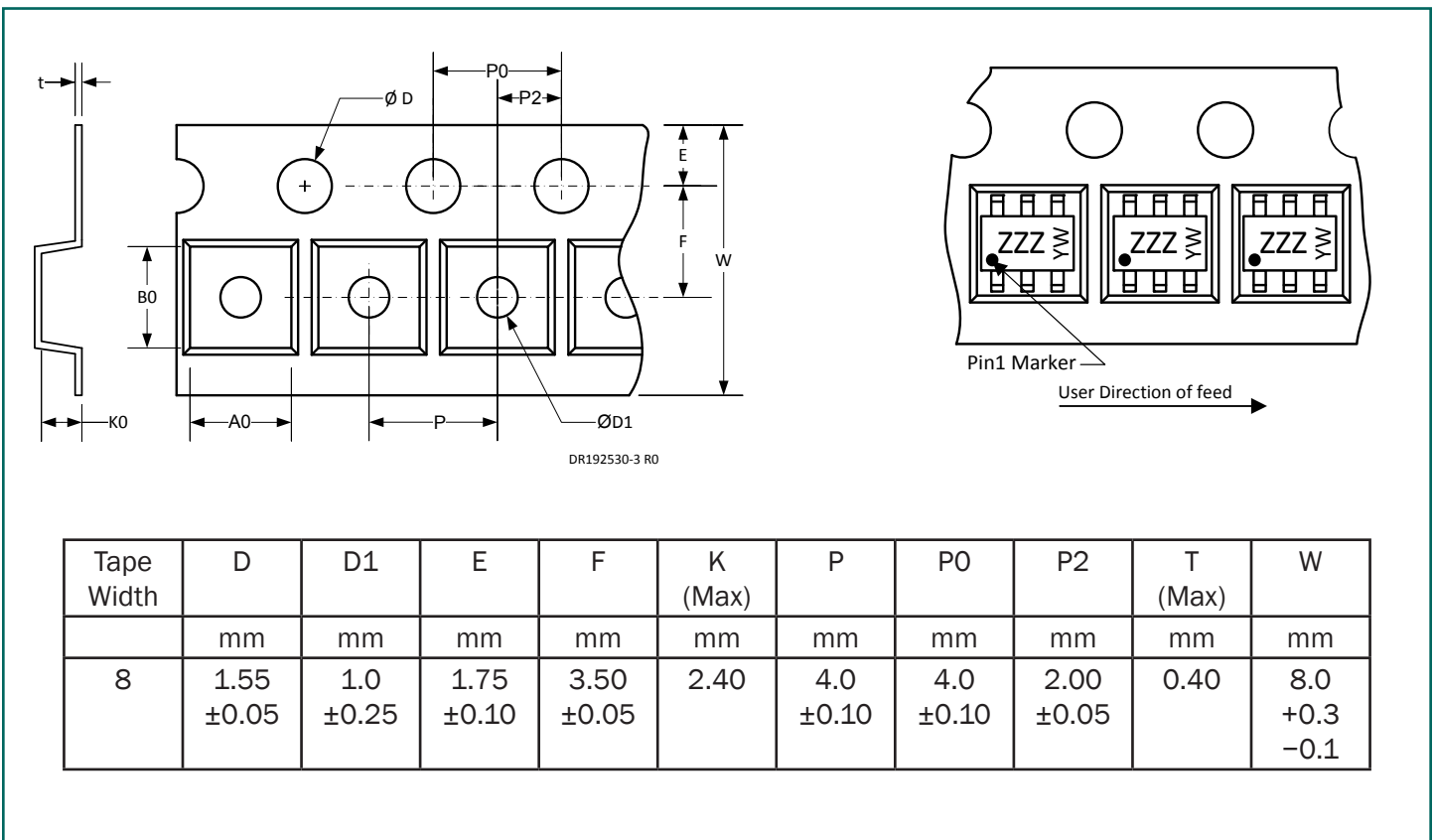
Notes:

ZZZ = Marking Code

YW = Alphanumeric character Date Code

See ordering information for part specific marking codes

## Tape and Reel Specification



## Ordering Information

Part Number	Working Voltage	Marking Code	Qty per 7 Inch Reel
TClamp0882S.TCT	8V	088	3000
TClamp1282S.TCT	12V	128	3000
TClamp2082S.TCT	20V	208	3000
TClamp2482S.TCT	24V	248	3000

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